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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: Wen-Chou Vincent Wang, *et al.*

Attorney Docket No.:
ALTRP100/A1198

Application No.: 10/719,218

Examiner: Shrinivas H. Rao

Filed: November 20, 2003

Group: 2814

Title: STRUCTURE, MATERIAL AND DESIGN
FOR ASSEMBLING A LOW-K Si DIE TO
ACHIEVE AN INDUSTRIAL GRADE
RELIABILITY WIRE BONDING PACKAGE

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the U.S. Postal Service with sufficient postage as first-class mail on April 18, 2005 in an envelope addressed to the Commissioner for Patents, P.O. Box 1450 Alexandria, VA 22313-1450.

Signed:

Tomika D. Thomas

REQUEST FOR STATUS

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir:

Applicant hereby requests status of the above-referenced patent application. This application was filed on November 20, 2003 and no response has been received as of this date.

Respectfully submitted,

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